

FEATURES :

- HIGH POWER
 $P_{1dB} = 46 \text{ dBm at } 2.6 \text{ GHz}$
- HIGH GAIN
 $G_{1dB} = 12 \text{ dB at } 2.6 \text{ GHz}$
- PARTIALLY MATCHED TYPE
- HERMETICALLY SEALED PACKAGE

RF PERFORMANCE SPECIFICATIONS ($T_a = 25^\circ\text{C}$)

CHARACTERISTICS	SYMBOL	CONDITION	UNIT	MIN.	TYP.	MAX.
Output Power at 1dB Compression Point	P_{1dB}	$V_{DS} = 10 \text{ V}$ $f = 2.6 \text{ GHz}$	dBm	45.0	46.0	—
Power Gain at 1dB Compression Point	G_{1dB}		dB	11.0	12.0	—
Drain Current	I_{DS}		A	—	8.0	9.0
Power Added Efficiency	η_{add}		%	—	47	—
Channel-Temperature Rise	ΔT_{ch}	NOTE 1	$^\circ\text{C}$	—	—	90

ELECTRICAL CHARACTERISTICS ($T_a = 25^\circ\text{C}$)

CHARACTERISTICS	SYMBOL	CONDITION	UNIT	MIN.	TYP.	MAX.
Transconductance	g_m	$V_{DS} = 3 \text{ V}$ $I_{DS} = 8.0 \text{ A}$	mS	—	8000	—
Pinch-off Voltage	V_{GSoff}	$V_{DS} = 3 \text{ V}$ $I_{DS} = 140 \text{ mA}$	V	-1.0	-3.0	-4.0
Saturated Drain Current	I_{DSS}	$V_{DS} = 3 \text{ V}$ $V_{GS} = 0 \text{ V}$	A	—	20	26
Gate-Source Breakdown Voltage	V_{GSO}	$I_{GS} = -500 \mu\text{A}$	V	-5	—	—
Thermal Resistance	$R_{th(c-c)}$	Channel to Case	$^\circ\text{C/W}$	—	0.8	1.2

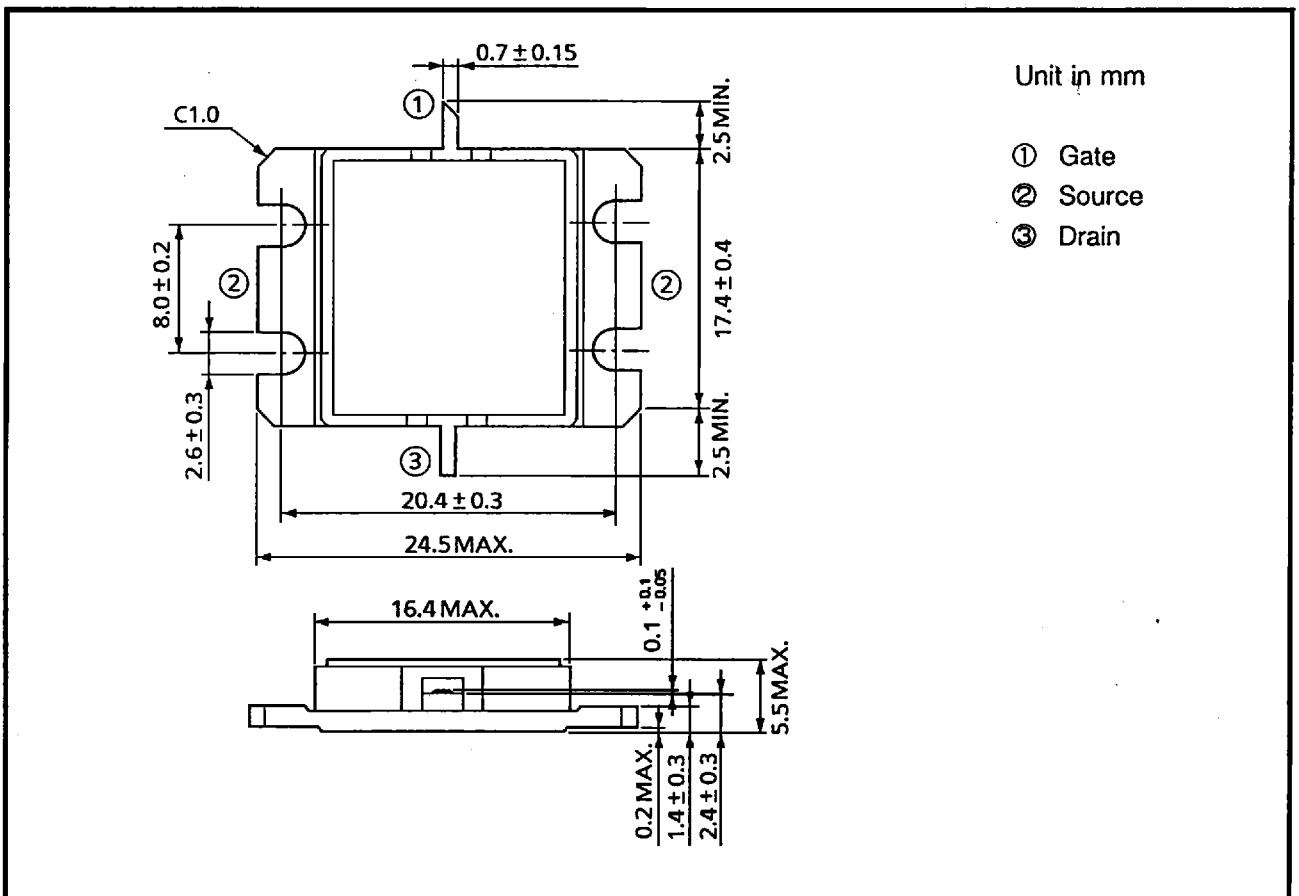
NOTE 1: $\Delta T_{ch} = (V_{DS} \times I_{DS} + P_{in} - P_{1dB}) \times R_{th(c-c)}$

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ABSOLUTE MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTICS	SYMBOL	UNIT	RATING
Drain-Source Voltage	V _{DS}	V	.15
Gate-Source Voltage	V _{GS}	V	-5
Drain Current	I _{DS}	A	26
Total Power Dissipation (T _C = 25°C)	P _T	W	100
Channel Temperature	T _{ch}	°C	175
Storage Temperature	T _{stg}	°C	-65~175

PACKAGE OUTLINE (2-16G1B)



HANDLING PRECAUTIONS FOR PACKAGED TYPE

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.